

# SOT1857-1

plastic ultra thin fine-pitch land array package: 64 lands

1 November 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	UFLGA64
<b>Package outline version code</b>	SOT1857-1
<b>Manufacturer package code</b>	SOT1857
<b>Package type industry code</b>	UFLGA
<b>Package outline version description</b>	plastic ultra thin fine-pitch land array package: 64 lands
<b>Package style descriptive code</b>	UFLGA
<b>Package body material type</b>	P
<b>Mounting method type</b>	S (surface mount)
<b>Package life cycle status</b>	REL
<b>Security status</b>	COMPANY PUBLIC
<b>Issue date</b>	4-4-2016
<b>Customer specific indicator</b>	N
<b>Maturity</b>	Product

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	64	-	



## 2. Package outline

UFLGA64: plastic ultra thin fine-pitch land grid array package; 64 lands SOT1857-1

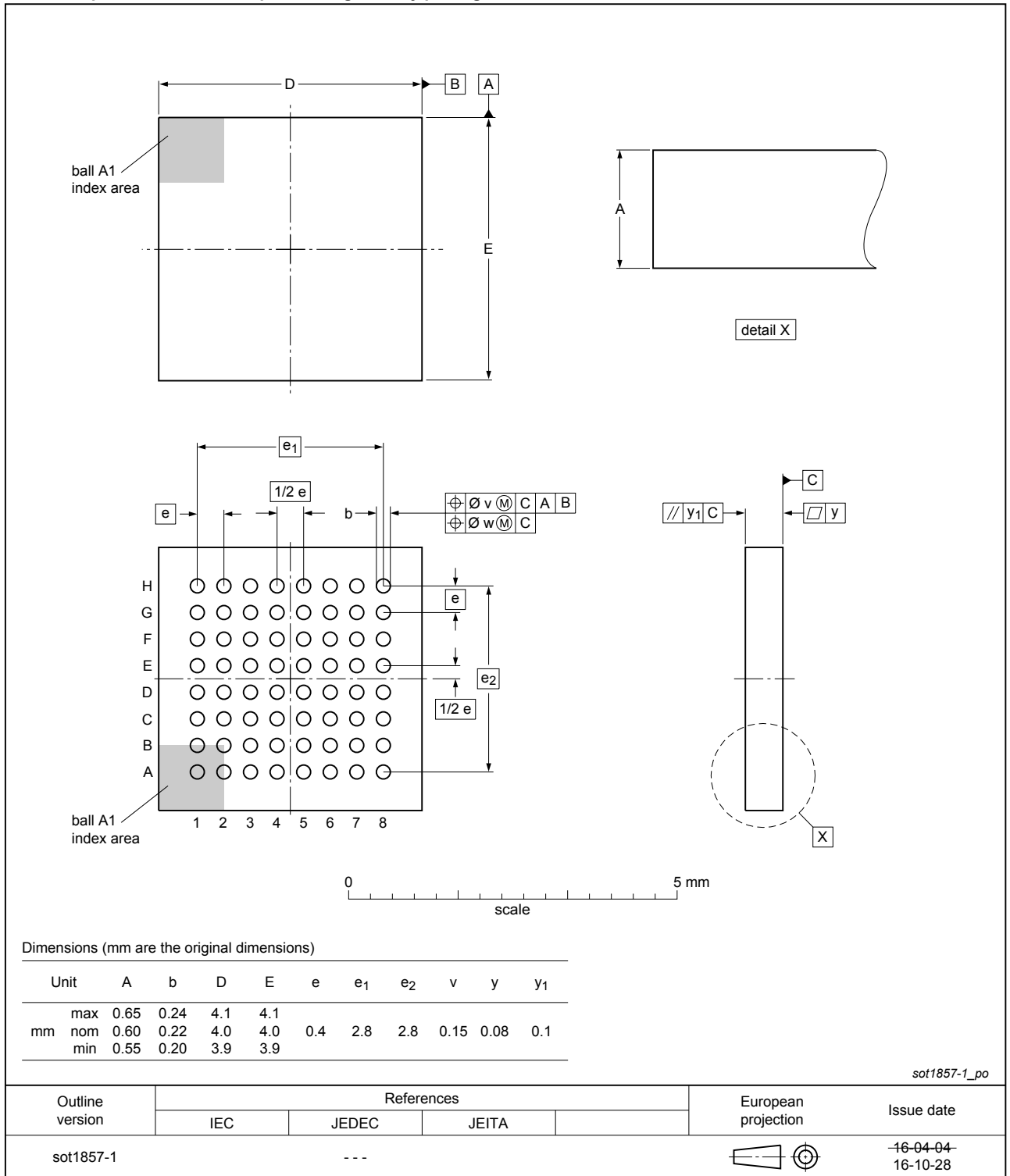


Fig. 1. Package outline UFLGA (SOT1857-1)

### 3. Legal information

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